

SID

Factory: Rot am See

Article:

457

ML4

Provided:

Kracht, Enrico

Customer:

Date:

08.06.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
---------------	----------	----	---------	------------------

A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	A00 B00
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	170		2	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		3	
A-RS-FR4-ML-0.25mm-035+035-TG150-HF	50200654	35	L2	4	
		250			
		35	L3		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	170		5	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		6	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	7	

Thickness after Pressing

B00:

690 µm

Tol+:

80 µm

Tol-:

80 µm

Dmax:

770 µm

Dmin:

610 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

800 µm

Tol+:

80 µm

Tol-:

80 µm

Dmax:

880 µm

Dmin:

720 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

696 µm

Version 1.2.14.15

© Würth Elektronik